PCN # 1745A

DATE: April 27, 2018

EXPECTED PCN SHIP DATE: April 27, 2018



Quality Assurance 160 Rio Robles San Jose, CA 95134

www.maximintegrated.com

PROCESS CHANGE NOTICE	
X PRODUCT CHANGE NOTICE	
MAXIM INTEGRATED HEREBY ISSUES NOTIFICATION OF CHANGE THAT MAY AFFECT THE FOLLOWING CATEGORIES: DESIGN WAFER FAB X ASSEMBLY TEST ELEC/MECH SPECS	
AFFECTED PRODUCT:	
Ordering P/N: (See PN listing XLS in PCN ZIP file)	
CHANGE FROM: -	CHANGE TO: -
Maxim product MAX17543ATP in QFN package (4x4)	Product will use Pd-coated copper (Cu) bond wire (same 1.3 mil
assembled at ASE/CHUNG-LI/TAIWAN/R.O.C. (ASE-CL)	thickness). Assembler ASE-CL remain the same.
using 1.3 mil gold (Au) bond wire	
JUSTIFICATION: -	
Maxim is expanding the copper bond wire QFN production line at ASE-CL. ASE-CL has been manufacturing CuPd QFN products	
(2x2 thru 7x7) for several years.	
Reliability report attached (ref. 1745_R26466) shows ?Pass? qualification tests/results.	
There are no changes to the form, fit, or function of the devices.	
TRACEABILITY: Maxim Integrated maintains full traceability by device marking, packaging labels and shipment documents.	

Maxim Integrated's Change Notification System is designed to keep our customer base apprised of major product, manufacturing, or facility improvements.

Nasser Ali Chaouche

Nasser AliChaouche / PCN Coordinator

For further information, please contact either of the people listed below.

Contact your local Maxim Integrated Company Representative or

Nasser AliChaouche, PCN Coordinator 408-601-5660 / pcn.coordinator@maximintegrated.com

Document Title: Product Change Notice - Notification Only

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